

## N-Channel 25-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ)			
25	0.0027 at V <sub>GS</sub> = 10 V	36	49 nC			
	0.0032 at V <sub>GS</sub> = 4.5 V	29	49 110			

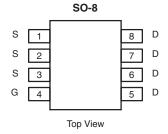
## **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Available**
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested

### **APPLICATIONS**

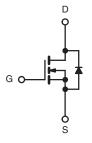
- Synchronous Buck Low Side
  - Notebook
  - Server
  - Workstation
- Synchronous Rectifier POL





Ordering Information: Si4630DY-T1-E3 (Lead (Pb)-free)

Si4630DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	25	V		
Gate-Source Voltage		V <sub>GS</sub>	± 16	v	
	T <sub>C</sub> = 25 °C		40		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C		32		
Continuous Diain Current (1) = 130 C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	27 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		21 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	70	^	
Ocations of Ocase Burin Binds Ocase	T <sub>C</sub> = 25 °C	I-	7.0		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	3.0 <sup>b, c</sup>		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	30		
Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	45	mJ	
	T <sub>C</sub> = 25 °C		7.8		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	5.0	10/	
	T <sub>A</sub> = 25 °C		3.5 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C		2.2 <sup>b, c</sup>		
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	29	35	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	13	16	0/ **	

### Notes:

- a. Based on T<sub>C</sub> = 25 °C.
  b. Surface Mounted on 1" x 1" FR4 board.
- t = 10 s.
- c. t = 10 s. d. Maximum under Steady State conditions is 80 °C/W.

## **Si4630DY**

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Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	25			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			28		1400	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 6		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.2	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$			± 100	nA	
Zana Oata Waltana Busin Oamant	I <sub>DSS</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current		$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
	В	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.0022	0.0027	$ \Omega$	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.0026	0.0032		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		120		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			6670		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		997			
Reverse Transfer Capacitance	C <sub>rss</sub>			531			
Total Cata Charres	Q <sub>g</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		107.5	161		
Total Gate Charge				49	73		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		15.7			
Gate-Drain Charge	Q <sub>gd</sub>			13.6			
Gate Resistance	$R_{g}$	f = 1 MHz		1.5	2.25	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			37	56		
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_L = 1.5\Omega$		122	185		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ 10 A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		47	71		
Fall Time	t <sub>f</sub>			15	23	ne	
Turn-On Delay Time	t <sub>d(on)</sub>			17	26	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 1.5 $\Omega$		93	140		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ 10 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		60	90		
Fall Time	t <sub>f</sub>			9	15		
<b>Drain-Source Body Diode Characterist</b>	ics						
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			7	Α	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				70	Λ	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 3 A		0.72	1.1	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			47	70	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 13 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		50	75	nC	
Reverse Recovery Fall Time	t <sub>a</sub>			23		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			24		113	

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

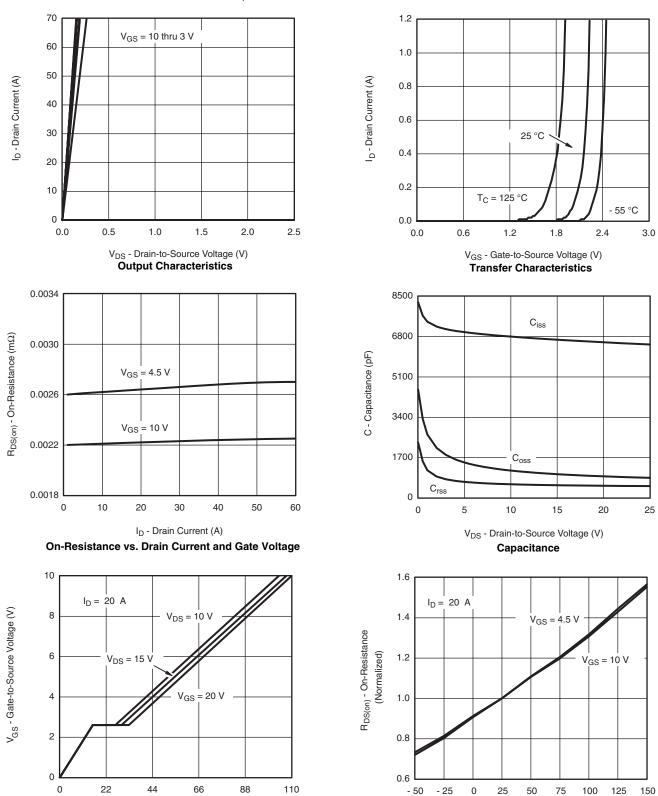
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Q<sub>q</sub> - Total Gate Charge (nC)

**Gate Charge** 

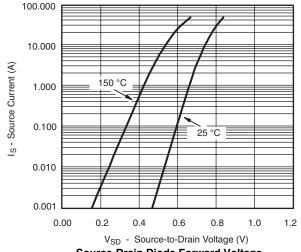
T<sub>J</sub> - Junction Temperature (°C)

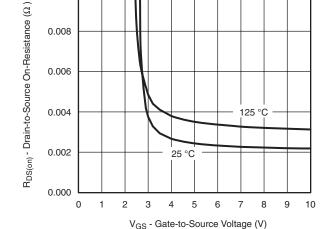
On-Resistance vs. Junction Temperature

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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

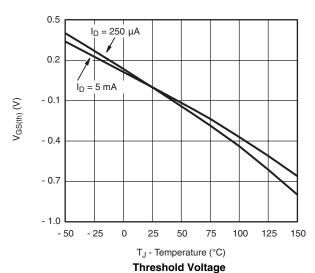


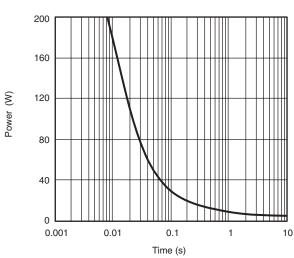


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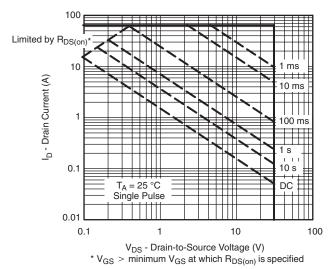
Source-Drain Diode Forward Voltage







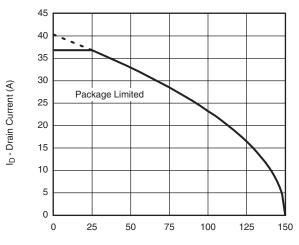
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

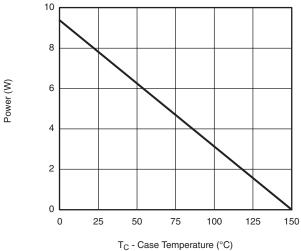


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

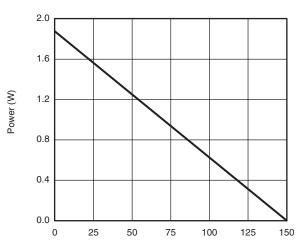


T<sub>C</sub> - Case Temperature (°C)

### **Current Derating\***







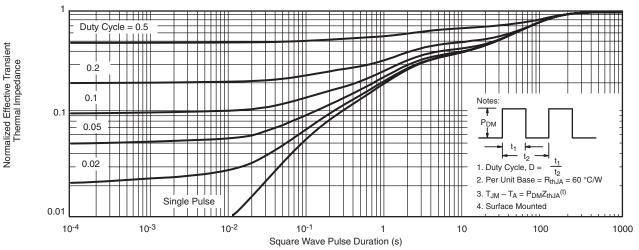
T<sub>A</sub> - Ambient Temperature (°C) Power, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

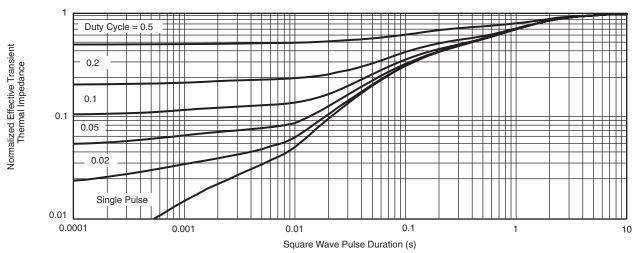
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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS		INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

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### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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